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(71) Applicant: CHIP COOLERS, INC. [US/US]; 333 Strawberry Field Road, Warwick, RI 02886 (US).

(72) Inventor: MCCULLOUGH, Kevin, A.; 11 Tiernan Avenue, Warwick, RI 02886 (US).

(74) Agents: JOSEPHS, David, R. et al.; Barlow, Josephs & Holmes, Ltd., 5th floor, 101 Dyer Street, Providence, RI 02903 (US).

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(54) Title: THERMALLY CONDUCTIVE COMPOSITE MATERIAL

(57) Abstract

A conductive molding composition (100), with a thermal conductivity above 22 W/m²K, is provided. The thermally conductive composition (100) includes a polymer base matrix (12) of, by volume, between 30 and 60 percent. A first thermally conductive filler (116), by volume, between 25 and 60 percent is provided in the composition that has a relatively high aspect ratio of at least 10:1. Also in the composition mixture (100) is a second thermally conductive filler (114), by volume, between 10 and 25 percent that has a relatively low aspect ratio of 5:1 or less.

